Fairchild Semiconductor Product Package Material Disclosure

Package Type	BGA 3.5 x 4.0 (FLF BGA)						
Weight of Package (grams)	5.71E-02						
Component	Material	Weight in grams	Substance in material	Wt% in component	Wt% in finished product	CAS #	Parts per Million
Frame	Copper Alloy	4.86E-02			85.20		852036
			Copper	96.08	81.86	7440-50-8	818636
			Iron	2.40	2.04	7439-89-6	20449
			Zinc	0.13	0.11	7440-66-6	1108
			Nickel (plate)	0.95	0.81	7440-02-0	8094
			Palladium (plate)	0.38	0.32	7440-05-3	3238
			Gold (plate)	0.06	0.05	7440-57-5	511
Chip	Silicon and inorganic compounds	3.58E-03			6.27		62732
			Silicon and trace metals	100.00	6.27	7440-21-3	62732
Die attach	Solder	1.38E-03			2.42		24182
			Tin	91.50	2.21	7440-31-5	22126
			Antimony	8.50	0.21	1309-64-4	2055
Solder Balls	Pb-free Solder	3.40E-03			5.96		59578
			Tin	95.20	5.67	7440-31-5	56718
			Silver	3.80	0.23	7440-22-4	2264
			Copper	1.00	0.06	7440-50-8	596
Terminal Finish	Pb-free Solder	8.40E-05			0.15		1472
			Nickel	95.60	0.14	7440-02-0	1407
			Palladium	3.80	0.01	7440-05-3	56
			Gold	0.60	0.00	7440-57-5	9

Materials Disclosure Disclaimer

The information provided in this Materials Disclosure is, to our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company. Also, there may not be information included in this statement regarding the minute amounts of dopant and metal materials contained within the electrically active or passive devices contained within the finished product.